



Republic of the Philippines
EASTERN VISAYAS STATE UNIVERSITY
 Tacloban City

BID SUPPLEMENT

Date: October 19, 2023

Title: IB-2023-09-12 PROCUREMENT OF SMART CAMPUS ENHANCEMENT PROGRAM OF EASTERN VISAYAS STATE UNIVERSITY (EVSU)

Reference No.: 10194420

SUPPLEMENTAL/BID BULLETIN No. 1

This Supplemental/Bid Bulletin is issued to all prospective bidders to clarify, modify and/or amend items in the Bidding Documents as discussed and agreed during the Pre-Bid Conference held on October 13, 2023 for the above-mentioned procurement project. This shall form an integral part of the Bid Documents.

I. GENERAL QUERIES

REFERENCE	QUERIES	AMMENDMENTS/ CLARIFICATIONS
<p>Section I. Invitation to Bid (Clause 7)</p> <p>7. Bids must be duly received by the BAC Secretariat on or before:</p> <p>a. Online or Electronic submission of bids. Bidders may submit their electronic bids through email at vsu.bacsecretariat@evsu.edu.ph on or before October 27, 2023, 10:00 A.M. (Further instructions on the submission and receipt of electronic bids will be posted through a bid bulletin); and,</p> <p>b. Manual submission of bids. Bidders who submit their bids electronically must submit a hard copy of the bids as this shall be the basis for the evaluation and assessment during the Post-Qualification on or before November 6, 2023, 1:00 P.M. at the address indicated below.</p>	<p>Do we have to submit our bids both via electronically and manually for the purposes of submission or is manual submission of bids sufficient as the BAC basis for evaluation purposes?</p>	<p>Section I. Invitation to Bid (Clause 7)</p> <p>8. Bids must be duly received by the BAC Secretariat on or before:</p> <p>a. Online or Electronic submission of bids. Bidders may submit their electronic bids through email at vsu.bacsecretariat@evsu.edu.ph on or before October 27, 2023, 10:00 A.M. (Further instructions on the submission and receipt of electronic bids will be posted through a bid bulletin); and, The bidder has the option to submit bid electronically or manually on or before October 27, 2023, 10:00 A.M. If a bidder chooses to submit an electronic bid, the same bidder shall submit a bid manually for the same project on or before November 6, 2023, 1:00 P.M., for evaluation purposes during post-Qualification. Further instructions on the submission and receipt of electronic bids are provided in in Annex "A".; and,</p> <p>b. Manual submission of bids. Bidders who submit their bids electronically must submit a hard copy of the bids as this shall be the basis for the evaluation and assessment during the Post-Qualification on or before November 6, 2023, 1:00 P.M. at the address indicated below. If a bidder chooses to submit manually, the manual bid shall be sufficient for evaluation purposes during the Opening of Bids, and electronic submission shall no longer be required. However, for item no. 3.24.1 – 3.24.2 of Section VII. Technical Specifications, the bidder must also submit soft copies in PDF on or before the deadline of submission of bids on November 6, 2023, 1:00 P.M. to</p>

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	<p>Regarding the bidding timeline, the submission is 2 weeks from now, given the size and scope of the project and the complexity, can the Procuring Entity consider extending the submission of bids?</p>	<p><i>evsu.bacsecretariat@evsu.edu.ph. Instructions on the electronic submission is provided in Annex "A".</i></p> <p>The same schedule will be followed based on our target timeline to complete the procurement activities within the shortest reasonable period for the delivery and implementation of this project, and also in consideration of the validity of appropriations of the funding source (General Appropriations Act of 2023) of its duly approved budget.</p>
<p>Section II. Instruction to Bidders (Clause 10.2) vs. Section III. Bid Data Sheet (Clause 5.3 (b))</p> <p><u>Instruction to Bidders</u> 10.2 The Bidders SLCC as indicated in ITB Clause 5.3 should have been completed within <i>two (2)</i> years prior to the deadline for the submission and receipt of bids.</p> <p><u>Bid Data Sheet</u> 5.3 (b) Completed within <i>five (5)</i> years prior to the deadline for the submission and receipt of bids.</p>	<p>For Purposes of Bid Submission and bid evaluation, which one should govern?</p>	<p><u>Section II. Instruction to Bidders (Clause 10.2)</u></p> <p>10.2 The Bidders SLCC as indicated in ITB Clause 5.3 should have been completed within two (2) five (5) years prior to the deadline for the submission and receipt of bids.</p>
<p>2.1.3.1. Fabrication Laboratory</p> <p>The winning bidder shall be responsible for the physical fit-out works, supply of essential equipment, testing, and commissioning of the ff:</p> <ul style="list-style-type: none"> 2.1.3.1.5. Laser Cutter 2.1.3.1.6. Laser Engraver 2.1.3.1.7. Small Milling Machine 2.1.3.1.8. Electronics Workbench 2.1.3.1.9. Big Milling Machine ShopBot CSE router 2.1.3.1.10. Sewing Embroidery Machine 	<p>Can we be provided with the specifications of the following requirements to be provided for the Fabrication Laboratory?</p>	<p>Specifications of the equipment requirements to be provided for the Fabrication Laboratory is provided in Section 3.1.2 as amended to wit:</p> <p>3.1.2. Command and Control Center Facility</p> <ul style="list-style-type: none"> 3.1.2.1. Technical working and monitoring area for System, Network, Security, and Applications Administrators/Operators 3.1.2.2. Provision of 4 x 55" wall-mounted LED Monitors 3.1.2.3. Supply of Desktop Computers for Network, Security, and Applications Performance Monitoring, compliant with the following minimum specifications: <ul style="list-style-type: none"> 3.1.2.3.1. Processor: Intel Core i7-12th 13th Gen 3.1.2.3.2. Operating System: Windows 11 Pro 3.1.2.3.3. RAM: at least 16GB DDR4 3.1.2.3.4. Storage: at least 1TB SSD 3.1.2.3.5. Video Adapter: at least 4GB Discrete GPU

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		<p>3.1.2.3.6. Display: at Least 24" monitor (1920 x 1080)</p> <p>3.1.2.3.7. Network Interface: At least with Wi-Fi, Bluetooth and RJ45 port</p> <p>3.1.2.3.8. Standard I/O Ports: USB 3.2 Gen 2 Type-A, USB 3.2 Gen 1 Type-A, USB 3.2 Gen 2 Type-C & HDMI port</p> <p>3.1.2.3.9. Standard Keyboard and Mouse</p> <p>3.1.2.4. Separate UPS configured as N+1 must be provided</p> <p>3.1.2.5. Provision of all essential furnishings, (No OSM)</p> <p>3.1.3 Supply delivery and installation of (30 units) Desktop Computers with 1 kVA UPS for the Fabrication Lab Training Room (Refer to 3.1.2.3 for the minimum Specifications):</p> <p>3.1.4 Supply delivery and installation of (8 units) Access point with the following requirement and specifications:</p> <p>3.1.4.1. 802.11n version 2.0 (and related) capabilities</p> <p>3.1.4.1.1. 4x4 MIMO with four spatial streams</p> <p>3.1.4.1.2. 802.11n and 802.11a/g beamforming</p> <p>3.1.4.1.3. 20- and 40-MHz channels</p> <p>3.1.4.1.4. PHY data rates up to 890 Mbps (40 MHz with 5 GHz and 20 MHz with 2.4 GHz)</p> <p>3.1.4.2. 802.11ac</p> <p>3.1.4.2.1. 4x4 downlink MU-MIMO with four spatial streams</p> <p>3.1.4.2.2. MRC</p> <p>3.1.4.2.3. 802.11ac beamforming</p> <p>3.1.4.2.4. 20-, 40-, 80-, and 160-MHz channels</p> <p>3.1.4.2.5. PHY data rates up to 3.47 Gbps (160 MHz with 5 GHz)</p> <p>3.1.4.3. 802.11ax</p> <p>3.1.4.3.1. 4x4 downlink MU-MIMO with four spatial streams</p> <p>3.1.4.3.2. Uplink/downlink OFDMA</p> <p>3.1.4.3.3. TWT</p> <p>3.1.4.3.4. BSS coloring</p> <p>3.1.4.3.5. MRC</p>

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		<p>3.1.4.3.6. 802.11ax beamforming</p> <p>3.1.4.3.7. 20-, 40-, 80-, and 160-MHz channels</p> <p>3.1.4.3.8. PHY data rates up to 5.38 Gbps (160 MHz with 5 GHz and 20 MHz with 2.4 GHz)</p> <p>3.1.4.4. System Memory</p> <p>3.1.4.4.1. 2048 MB DRAM</p> <p>3.1.4.4.2. 1024 MB flash</p> <p>3.1.4.5. Ports</p> <p>3.1.4.5.1. 1x 100, 1000, 2500 Multigigabit Ethernet (RJ-45) – IEEE 802.3bz</p> <p>3.1.4.5.2. Auto-MDIX support</p> <p>3.1.4.5.3. Management console port (RJ-45)</p> <p>3.1.4.5.4. USB 2.0 @ 4.5W</p> <p>3.1.4.6. Deployment</p> <p>3.1.4.6.1. Compatible with Wireless LAN Controller C9800</p> <p>3.1.5 Supply delivery and installation of five (5) units Integrated All-in One 85” Interactive Collaboration Board with Digital Board installed on both sides and Audio System and Front and Rear Tracking Cameras</p> <p>3.1.5.1 All-in-One Collaboration Board</p> <p>The All-in-one terminal should include:</p> <p>3.1.5.1.1 Interactive Panel;</p> <p>3.1.5.1.2 Video conference codec;</p> <p>3.1.5.1.3 Built-in Speaker;</p> <p>3.1.5.1.4 Built-in microphone;</p> <p>3.1.5.1.5 Built-in camera.</p> <p>3.1.5.1.6 OPS module</p> <p>System configuration:</p> <p>3.1.5.1.7 8-core CPU, 8 GB RAM, 64 GB Flash</p> <p>3.1.5.1.8 With an OPS module/computer with: i7-13th Gen, DDR4 16 GB, 512 C SSD, Windows10 IOT Enterprise SAC Features</p> <p>3.1.5.1.9 Supports anti-glare</p> <p>3.1.5.1.10 Automatically adjusts screen brightness based on light sensing.</p> <p>3.1.5.1.11 Optical anti-blue light: protects eyes and doesn't change color.</p>

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		<p>3.1.5.1.12 Screen response time: 8ms</p> <p>3.1.5.1.13 Touch accuracy: ±1mm</p> <p>3.1.5.1.14 Supports 20 touchpoints</p> <p>3.1.5.1.15 4K built-in camera</p> <p>3.1.5.1.16 A built-in privacy cover to physically close the camera</p> <p>3.1.5.1.17 Auto-framing: automatically adjusts the camera based on the location of the participants. The camera displays all participants in a panoramic view and ensures that the participants are displayed in the center.</p> <p>3.1.5.1.18 Speaker tracking, automatically switch to the close-up picture of speaker without manual intervention</p> <p>3.1.5.1.19 At least 6 built-in microphone arrays</p> <p>3.1.5.1.20 The microphone sound pickup radius at least 12 meters, and the sound pickup angle: 180°.</p> <p>3.1.5.1.21 Acoustic echo cancellation (AEC), automatic gain control (AGC), automatic noise reduction (ANR)</p> <p>3.1.5.1.22 Can add external microphone</p> <p>3.1.5.1.23 Two built-in speakers, frequency response range:100Hz-20KHz, total power not less than 40 W</p> <p>3.1.5.1.24 Video In: 1 x HDMI 2.0 (4K60)</p> <p>3.1.5.1.25 Video Out: 1 x HDMI 2.0 (4K60)</p> <p>3.1.5.1.26 Audio In: 1 x 3.5mm</p> <p>3.1.5.1.27 Audio Out: 1 x 3.5mm</p> <p>3.1.5.1.28 1x Omni-directional microphone port, support the cascading of two microphones.</p> <p>3.1.5.1.29 3x USB Type-A 3.0, support USB flash drive, mouse, keyboard, microphone, speaker, remote control and wireless dongle for projection.</p> <p>3.1.5.1.30 1x USB Type-C, support USB flash device, wireless dongle for projection.</p> <p>3.1.5.1.31 1x 10/100/1000M RJ45 port</p> <p>3.1.5.1.32 Wi-Fi 5 and Wi-Fi 6, IEEE802.11a/b/g/n/ac/ax network protocol</p> <p>3.1.5.1.33 Remote control that controls the volume, speaker on/off, microphone mute/unmute, camera open/close, previous/next page</p> <p>3.1.5.1.34 Writing latency of no more than 16ms</p> <p>3.1.5.1.35 The built-in whiteboard supports handwriting, drawing, erasing, marking, saving, zooming, and locking the whiteboard. The background color can be changed.</p> <p>3.1.5.1.36 The whiteboard supports page turning. A maximum of 100 pages are supported</p> <p>3.1.5.1.37 Selectable pen type: pencil, pen, and highlighter. Pen color: color palette.</p> <p>3.1.5.1.38 Full-screen annotation: You can take a screenshot of any screen to enter the whiteboard annotation</p>

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		<p>3.1.5.1.39 The contents of the whiteboard can be saved locally and edited when you open it for the second time, saved in an external USB flash memory, sent to an email.</p> <p>3.1.5.1.40 When writing on the electronic whiteboard, the hand-drawn graphics can be recognized as standard geometric figures, and the hand-written text can be recognized as standard printed text.</p> <p>3.1.5.1.41 Wired projection through HDMI cable. Projection resolution support up to 1080p60fps and 4K30fps.</p> <p>3.1.5.1.42 Wired projection through USB Type-C cable. Projection resolution support up to 1080p60fps and 4K30fps. When PC is projected to the device, the device can control the PC reversely without extra cables.</p> <p>3.1.5.1.43 Wireless projection by entering the projection code on the mobile phone and PC. Projection resolution supports up to 1080p60fps and 4K15fps. When PC is projected to the device, the device can control the PC reversely.</p> <p>3.1.5.1.44 Wi-Fi Direct projection. Users do not need to configure a Wi-Fi router or change the network of their mobile phones or PCs during screen projection. Projection resolution: up to 1080P60fps and 4K15fps. When PC is projected to the device, the device can control the PC reversely.</p> <p>3.1.5.1.45 DLNA projection, during projection, user can use mobile phone to perform other tasks.</p> <p>3.1.5.1.46 Allows users to use the same projection APP to project screens to OPS Windows.</p> <p>3.1.5.1.47 Supports third-party video conference APP</p> <p>3.1.5.1.48 The camera, microphone and speaker can be used for third-party video conference APP.</p> <p>3.1.5.1.49 The camera auto-framing and voice tracking features can be used for third-party video conference APP</p> <p>3.1.5.1.50 Android apps can be installed.</p> <p>3.1.5.1.51 Support APP store dedicated to large screens device.</p> <p>3.1.5.1.52 Supports APIs, third-party applications can perform registration, conference call, conference control, configuration query, and address book query based on the APIs.</p> <p>3.1.5.1.53 Multi-window: The desktop can be divided into two windows that display two applications. User can change the size of the two windows by dragging the windows.</p> <p>3.1.5.1.54 Supports BYOM, device hardware capabilities such as microphones, cameras, speakers, and touchscreen can be easily used as peripherals for 3rd party conferences on PC, by using Type-C cables, projection app, or wireless dongle</p>

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		<p>3.1.5.1.55 Welcome page without OPS module, the welcome page should contain text and pictures. The font of the text can be edited and the pictures can be customized.</p> <p>3.1.5.1.56 Users can quickly customize applications on the home page. Common applications can be placed on the home page for quick search. At least six applications can be configured on the home page.</p> <p>3.1.5.1.57 Supports dynamic wallpapers and static wallpapers. Wallpapers can be changed and imported.</p> <p>3.1.5.1.58 Clone screen content to another screen via HDMI cable</p> <p>3.1.5.1.59 Supports the OTA (over the air) technology.</p> <p>3.1.5.1.60 Supports password complexity settings</p> <p>3.1.5.2 Tracking Cameras</p> <p>3.1.5.2.1 Ultra 4K camera</p> <p>3.1.5.2.2 1/2.5", CMOS, Effective Pixel: 8.51M</p> <p>3.1.5.2.3 8x digital zoom</p> <p>3.1.5.2.4 H.265 compression</p> <p>3.1.5.2.5 Built-in advanced image recognition and tracking algorithm; can easily realize fluent and continuous tracking.</p> <p>3.1.5.2.6 Autofocus non-distortion lens, view angle 46° / 84° / 120° for options (120° don't support AF), a small lens with big view, supporting electronic PTZ</p> <p>3.1.5.2.7 Ultra-high noise ratio of the new CMOS image sensor can effectively reduce the low noise in the case of image noise, while the application of 2D and 3D noise reduction algorithm, significantly reducing the image noise, even under low light conditions, still keep the picture clean and clear, the image signal to noise ratio up to 55dB or more</p> <p>3.1.5.2.8 Supports PoE</p> <p>3.1.5.2.9 Interleaving mode: achieve single camera and single SDI interface to simultaneously output panoramic and close-up signals.</p> <p>3.1.5.2.10 Wall mount bracket of box camera</p> <p>3.1.5.3 Digital Board</p> <p>3.1.5.3.1 Integrated to the all-in-one conferencing board; installed on both sides</p> <p>3.1.5.3.2 1114mm X 1157.1mm in dimension and green color</p> <p>3.1.5.3.3 With an integrated document capture camera</p> <p>3.1.5.4 Audio System</p>

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		<p>3.1.5.4.1 3 x condenser hanging microphones per classroom installed on the ceiling</p> <p>3.1.5.4.2 Cardioid pattern</p> <p>3.1.5.4.3 70 dB SNR</p> <p>3.1.5.4.4 Central mixing console at the center classroom and a power amplifier</p> <p>3.1.5.4.5 Mixing console: 16-channel mixing console, 16-line inputs, 1-knob compressor, rack-mountable</p> <p>3.1.5.4.6 Power amplifier: 60 watts rated power, 2U rack mount, 4-16 ohms speaker output</p> <p>3.1.5.4.7 Small mixer for the side classrooms: integrated USB, reverb, echo and delay function, 4 mic inputs</p> <p>3.1.5.4.8 2 x 35 watts wall speakers per classroom</p> <p>3.1.5.4.9 Supply and termination of audio cables</p> <p>3.1.5.4.10 With HDMI splitter and cabling</p> <p>3.1.6. Supply delivery and installation of three (3) units 3D Professional Scanner.</p> <p>3.1.6.1 Capable of capturing the dimensions, measurements, and features of a real-world object, space, or human in seconds to construct an equivalent, digital 3D model.</p> <p>3.1.7. Supply delivery and installation thirty (30 licenses) Office productivity software with latest perpetual version.</p> <p>3.1.8. Supply delivery and installation two (2) units 3D Printer for Fabrication Lab with at least 1 yr. supply of accessories</p> <p>3.1.8.1 Automated resin fill system</p> <p>3.1.8.2 Build volume of 14.5 × 14.5 × 18.5 cm (WxDxH)</p> <p>3.1.8.3 Layer thickness of 25 – 300 microns</p> <p>3.1.8.4 XY resolution of at least 85 microns</p> <p>3.1.8.5 Equipped with at least 1 resin cartridge</p> <p>3.1.8.6 100 – 240VAC Power requirement</p> <p>3.1.8.7 Wireless connectivity to through WiFi 2.4GHz, 5GHz</p> <p>3.1.8.8 Wired connectivity through at USB 2.0</p> <p>3.1.8.9 Equipped with interactive touchscreen</p> <p>3.1.8.10 Equipped with various alerts such as touchscreen alerts, SMS/email alerts via dashboard, 2 LED status indicators and speaker for audio alerts</p> <p>3.1.9. Supply delivery and installation four (4) units Printer with continuous ink (wifi ready and multifunction)</p>

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		<p>3.1.10. Supply delivery and installation four (4) units 10X Optical Zoom Video Conferencing Kit Camera and four (4) units Video Conferencing Speakerphone with Built-in 2 Microphones Array.</p> <p>3.1.11. Supply delivery and installation four (4) Laser cutter and engraving machine</p> <p>3.1.11.1. Engraving and cutting accuracy: 2500dpi</p> <p>3.1.11.2. Cooling method: water cooling (including water pump)</p> <p>3.1.11.3. Software support: CorelDraw</p> <p>3.1.11.4. Minimum shaped text: 2x2 mm (0.08x0.08 in)</p> <p>3.1.11.5. Material requirements: non-metallic materials</p> <p>3.1.11.6. Engraving speed: 1-300 mm/s (0.04-11.81 inch/s)</p> <p>3.1.11.7. Software environment: Windows XP, WIN7, WIN8, WIN10</p> <p>3.1.11.8. Positioning accuracy: 0.01mm (0.0004 inches)</p> <p>3.1.11.9. Minimum formed letter: 1x1 mm (0.04x0.04 in)</p> <p>3.1.11.10. Free Velocity: 1-200 mm/sec (0.04-7.87 in/sec)</p> <p>3.1.11.11. Cutting Speed: 1-10 mm/sec (0.04-0.39 in/sec)</p> <p>3.1.12. Supply delivery and installation one (1) Small Milling Machine</p> <p>3.1.12.1. Engraving and cutting accuracy: 2500dpi Bench Drilling And Milling Machine 13-32mm High-power Multifunctional Industrial Heavy Duty 13-32mm</p> <p>3.1.12.2. Work Form: Milling</p> <p>3.1.12.3. Maximum processing width: 20</p> <p>3.1.12.4. Max processing length: 20</p> <p>3.1.12.5. Specifications: 13V drilling and milling machine power 550W, 16V drilling and milling machine power 600W, 20V drilling and milling machine power 850W, 25V drilling and milling machine power 1000W, 28V drilling and milling machine power 1250W, 36V drilling and milling machine power 2.2KW, two-axis electronic ruler, three-axis electronic ruler</p> <p>3.1.12.6. Scope of application: dedicated</p> <p>3.1.12.7. Maximum machining thickness: 20</p> <p>3.1.12.8. Weight: 140</p> <p>3.1.12.9. Rated voltage: 220</p> <p>3.1.12.10. Main motor power: 850W</p> <p>3.1.12.11. Dimensions: 610*560*900</p> <p>3.1.12.12. Processing customization: no</p>

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		<p>3.1.12.13. Overall weight: 140</p> <p>3.1.13. Supply delivery and installation one (1) Big Milling Machine ShopBot CSE router</p> <p>3.1.13.1. Working Area: 1200x1200x120mm</p> <p>3.1.13.2. Table Size: 1340X1545mm</p> <p>3.1.13.3. Traveling Positioning Accuracy: $\pm 0.03/300\text{mm}$</p> <p>3.1.13.4. Repositioning Positioning Accuracy: $\pm 0.04\text{mm}$</p> <p>3.1.13.5. Lathe Structure: Cast Steel</p> <p>3.1.13.6. X, Y Structure: Ball Screw, Shaft Linear Bearings</p> <p>3.1.13.7. Z Structure: Ball Screw, Shaft Linear Bearings</p> <p>3.1.13.8. Max. Consume Power: 3.5Kw</p> <p>3.1.13.9. Max. Speed: 0-18000mm/min</p> <p>3.1.13.10. Max. Working Speed: 0-8000mm/min</p> <p>3.1.13.11. Spindle Power Motor: 2.2kw water-cooling spindle</p> <p>3.1.13.12. Spindle Speed: 0-24000RPM</p> <p>3.1.13.13. Drive Mode: Stepper Motor</p> <p>3.1.13.14. Working Voltage: AC220V/50/60Hz</p> <p>3.1.13.15. Command: G Code, *uoo, *mmg, *plt</p> <p>3.1.13.16. Operating System: DSP or NC-STUDIO Control System</p> <p>3.1.13.17. Interface: USB</p> <p>3.1.13.18. Flash Memory: 128M</p> <p>3.1.13.19. Collet: ER20</p> <p>3.1.13.20. X-Y-Z Working Delicacy: $< 0.01\text{mm}$</p> <p>3.1.13.21. Software: Type3, Ucancam, Artcam</p> <p>3.1.13.22. Running circumstance: Temperature: $0^{\circ}\text{C}\sim 45^{\circ}\text{C}$ Relative humidity: 30%~75%</p> <p>3.1.13.23. Packing Size: 1800x1830x1450mm</p> <p>3.1.13.24. Net Weight: 600KG</p> <p>3.1.13.25. Gross Weight: 750KG</p> <p>3.1.14. Supply delivery and installation two (2) Sewing Embroidery Machine</p> <p>3.1.14.1. Type: Flat Embroidery Machine</p> <p>3.1.14.2. Operation: Computerized</p> <p>3.1.14.3. Overall Dimensions: 150*113*90 cm</p> <p>3.1.14.4. Power: 1500w</p> <p>3.1.14.5. Maximum Speed: 1200 RPM</p>

REFERENCE	QUERIES	AMMENDMENTS/ CLARIFICATIONS
		<p>3.1.14.6. Machinery Test Report: Provided</p> <p>3.1.14.7. Video outgoing-inspection: Provided</p> <p>3.1.14.8. Worktable Size: 80*80mm</p> <p>3.1.14.9. Head Interval: 500mm</p> <p>3.1.14.10. Embroidery Area: 400*500mm</p> <p>3.1.15. Supply delivery and installation four (4) Electronics Work Bench</p> <p>3.1.15.1. Tops supported by complete box-formed steel framework.</p> <p>3.1.15.2. 12-gauge steel top with 14-gauge reinforcement channels.</p> <p>3.1.15.3. Includes channel-shaped stringer that enhances rigidity.</p> <p>3.1.15.4. Panel leg design features a sleek, closed end that is both functional and good looking.</p> <p>3.1.15.5. Front panels (outlet panel) accept four duplex electrical outlets (requires wiring kit, sold separately).</p> <p>3.1.15.6. Load Capacity: 1800 lbs. evenly distributed</p> <p>3.1.15.7. Dimensions: 72" W x 30" D x 33-1/2" H</p> <p>3.1.15.8. Top Surface Material: Steel</p> <p>3.1.15.9. Top Surface Thickness: .1094"</p> <p>3.1.15.10. Base Type: Panel</p> <p>3.1.15.11. Base Material: Steel</p> <p>3.1.15.12. Base Color: Medium grey</p> <p>3.1.15.13. Floor Bolt: No</p> <p>3.1.15.14. Knockouts for Electrical Outlets: Yes (requires wiring kit for outlet functions)</p> <p>3.1.15.15. Stringer: Yes</p> <p>3.1.15.16. Weight: 187 lbs.</p>

REFERENCE	QUERIES	AMMENDMENTS/ CLARIFICATIONS
<p>3.1. Innovation Hub Building Development</p>	<p>May we request for guidance as to the total area of the 2nd Fl, 3rd Fl; and Roof Deck.</p> <p>For all of the floors, may we know the preferred dimension of all required rooms?</p> <p>Can the EVSU provide a drawing scheme as reference for proper space planning?</p>	<p>Specifications for this item is provided in Annex “B”.</p>
	<p>Is the demolition of existing structure part of the project or separate contractor will do?</p>	<p>Yes, it is part of the project. For the construction details of the Three (3)-Storey Innovation Hub Building, please refer to the Terms of Reference for the Infrastructure Component.</p>
<p>3.1. Innovation Hub Building Development</p> <p>3.1.5 Supply delivery and installation of five (5) units All-in-One 85” Interactive Collaboration Board with Digital Board installed on both sides and Audio System and Front and Rear Tracking Cameras</p> <p>3.1.5.1 All-in-One Collaboration Board</p>	<p>We would like to seek clarification as to the full requirements of the Interactive Board for this project.</p> <p>Prior to this pre-bid, we have conducted an initial market research on brands that can provide 85” Interactive Board. Unfortunately, none can comply with all the stated requirements. It seems that some requirements can be provided by one brand, while others by two or three different brands or models. Also, majority of the other requirements (tracking cameras, digital board, and audio system) are not built-in on the Interactive Board, they require integration, therefore will be non-compliant to the TOR.</p> <p>In this regard, may we know how we should go about this? Can the EVSU allow the Prospective Bidder to propose a standard 85” Interactive Board with integrated All-in-One conferencing camera with speaker, and microphone, to comply with the requirements.</p>	<p>Yes. This will require Integration from different brands or models.</p> <p>3.1.5 Supply delivery and installation of five (5) units Integrated All-in One 85” Interactive Collaboration Board with Digital Board installed on both sides and Audio System and Front and Rear Tracking Cameras</p>

REFERENCE	QUERIES	AMMENDMENTS/ CLARIFICATIONS
<p>3.2.6 Supply delivery and installation of Smart Campus Integrated Modules and at a minimum must consist of the following:</p> <p>3.2.6.1 8 units Turnstile with RFID.</p>	<p>May we know the exact location where the eight (8) turnstiles will be installed?</p>	<p>Four (4) Turnstiles will be located each at the Main Gate (Employees) and the Students Gate.</p>
<p>3.8. eLibrary Set Up</p> <p>3.8.1.6 2 Units Kiosk 3.8.1.8 1-unit RFID Monitor</p>	<p>May we be clarified on the intended purpose of the 2 units of kiosk under Section 3.8.1.6 of the eLibrary Set Up? Further, what will be the purpose of the RFID monitor if there is no RFID implementation in the eLibrary? Is this just a typo error?</p>	<p>The purpose of the 2 units of kiosk under Section 3.8.1.6 of the eLibrary Set Up is integrated to the eLibrary System so that Students can log-in, search for, choose, issue and return books on their own. The RFID is connected to the SMART Campus Integrated Modules.</p> <p>3.8.1.8 1 unit RFID Monitor Reader</p>
<p>3.9.1.9. CAD Software (preferably BIM, 1 lab for the CAAD and 1 for COE))</p> <p>3.9.1.9.1. Autodesk Fusion 360 3.9.1.9.2. Autodesk BIM 360 3.9.1.9.3. AutoCAD 3.9.1.9.4. Sketchup 3.9.1.9.5. 3DStudio Max</p>	<p>Our understanding is the prospective bidder will only supply at least 1 software. Kindly confirm if our understanding is correct.</p>	<p>This item shall be amended as follows:</p> <p>3.9.1.9. CAD Software (preferably BIM, 1 lab for the CAAD and 1 lab for COE))</p> <p>3.9.1.9.1. Autodesk Fusion 360 (20 licenses with 2 years subscription per lab) 3.9.1.9.2. Autodesk BIM 360 (20 licenses with 2 years subscription per lab) 3.9.1.9.3. AutoCAD (20 licenses with 2 years subscription per lab) 3.9.1.9.4. Sketchup (20 licenses with 2 years subscription per lab) 3.9.1.9.5. 3DStudio Max (20 licenses with 2 years subscription per lab)</p>
<p>3.10 Data Center Network Switches</p> <p>3.10.4.4 4 units Data Center Switch Alternating Current 1100W Power Supply Unit - Port Side Exhaust-<i>Cisco Switch</i></p> <p>3.10.4.13 2 units 715W AC 80+ platinum Config 1 Power Supply - <i>Cisco Switch</i></p> <p>3.10.4.36 715W AC 80+ platinum Config 1 Power Supply - <i>Cisco Switch</i></p>	<p>Can we request the same items to be deleted since these are pointing towards a Cisco model?</p>	<p>3.10. Data Center Network Switches</p> <p>3.10.1. 2 units Spine Switch Specifications:</p> <p>3.10.1.1. 36 x 40/100-Gbps QSFP28 ports 3.10.1.2. 4-core CPU 3.10.1.3. 24 GB System memory 3.10.1.4. 128GB SSD 3.10.1.5. RoHS Compliance 3.10.1.6. MTBF of 352,590 hours 3.10.1.7. Redundant power supply (N+1) 3.10.1.8. Redundant fan (4 fans) 3.10.1.9. Comprehensive protocol support for Layer 3 (v4/v6) unicast and multicast routing protocol suites, including BGP, Open Shortest Path First (OSPF), Enhanced Interior Gateway Routing Protocol (EIGRP), Routing Information Protocol Version 2 (RIPv2), Protocol Independent Multicast Sparse Mode (PIM-SM), Source-Specific Multicast (SSM), and Multicast Source Discovery Protocol (MSDP)</p>

REFERENCE	QUERIES	AMMENDMENTS/ CLARIFICATIONS
		<p>3.10.1.10. Quantity Requirement: Two (2)</p> <p>3.10.2. 2 units Leaf Switch Specifications (Border/Service/Compute/IP Storage):</p> <ul style="list-style-type: none"> 3.10.2.1. 48 x 1/10/25-Gbps and 6 x 40/100-Gbps QSFP28 ports 3.10.2.2. 6-core CPU 3.10.2.3. 128 SSD 3.10.2.4. 40MB System buffer 3.10.2.5. RoHS compliance 3.10.2.6. MTBF of 288,760 hours 3.10.2.7. Redundant power supply (N+1) 3.10.2.8. Redundant fan (4 fans) 3.10.2.9. Must have support for standards-based VXLAN EVPN fabrics, inclusive of hierarchical multi-site support. 3.10.2.10. Comprehensive protocol support for Layer 3 (v4/v6) unicast and multicast routing protocol suites, including BGP, Open Shortest Path First (OSPF), Enhanced Interior Gateway Routing Protocol (EIGRP), Routing Information Protocol Version 2 (RIPv2), Protocol Independent Multicast Sparse Mode (PIM-SM), Source-Specific Multicast (SSM), and Multicast Source Discovery Protocol (MSDP) 3.10.2.11. Quantity Requirement: Two (2) <p>3.10.3. 1 unit DMZ Switch Specifications:</p> <ul style="list-style-type: none"> 3.10.3.1. 24 ports 10/100/1000 3.10.3.2. 4x 1/10G fixed uplinks 3.10.3.3. Switching Capacity: 56 Gbps 3.10.3.4. Switch capacity with stacking: 136 Gbps 3.10.3.5. Forwarding Rate: 41 Mpps 3.10.3.6. Forwarding rate with stacking: 101 Mpps 3.10.3.7. DRAM: 2G 3.10.3.8. Flash: 4G 3.10.3.9. IP unicast routing protocols (including static, Routing Information Protocol Version 1 [RIPv1], RIPv2, RIPv6, and Open Shortest Path First [OSPF], Routed Access) 3.10.3.10. Advanced IP unicast routing protocols (including Full [OSPF], Enhanced Interior Gateway Routing Protocol [EIGRP], and Intermediate System-to-Intermediate System Version 4 [IS-ISv4]) 3.10.3.11. MTBF: 525,990 hrs.

REFERENCE	QUERIES	AMMENDMENTS/ CLARIFICATIONS
		<p>3.10.3.12 Redundant PSU</p> <p>3.10.3.13 SD-Access</p> <p>3.10.3.14. Bluetooth ready</p> <p>3.10.3.15. Perpetual licensing</p> <p>3.10.3.16 Quantity Requirement: One (1)</p> <p><i>3.10.4. Supply delivery and installation of Inter-active Data Center</i></p> <p><i>Network Switches at a minimum must consist of the following:-</i></p> <p>3.10.4.1 2 units Spine Switch, 36p 40/100G Quad Small Form Factor Pluggable (QSFP) 28</p> <p>3.10.4.2 4 units Data Center Switch Alternating Current 1100W Po Supply Unit Port Side Exhaust</p> <p>3.10.4.3 2 units Leaf Switch, 48p 1/10/25G, 6p 40/100G, Media Access Control Security (MACsec), SyncE</p> <p>3.10.4.4 4 units Data Center Switch Alternating Current 1100W Power Supply Unit Port Side Exhaust</p> <p>3.10.4.5 2 units Additional memory of 16GB for the Data Center Switches</p> <p>3.10.4.6 16 units 25 Gigabit Ethernet Small Form Factor Pluggable (25GBASE SR-SFP) Module</p> <p>3.10.4.7 1 unit DMZ Switch 24 port data only, 4 x 10G, Network Advantage</p> <p>3.10.4.8 1 unit 125W AC Config 5 Power Supply Secondary Power Supply</p> <p>3.10.4.9 5 units 600W AC Config 5 Power Supply Secondary Power Supply</p> <p>3.10.4.10 4 units Network Switch Stacking Module</p> <p>3.10.4.12 2 units Data Center Switch 24x25G Fiber Ports, modular uplink Switch</p> <p>3.10.4.13 2 units 715W AC 80+ platinum Config 1 Power Supply</p> <p>3.10.4.17 5 units Data Center Switch 24 port PoE+, 4 x 10G, Network Advantage</p> <p>3.10.4.18 5 units Wi-Fi 6 Outdoor Access Point, External Antenna, ROW Regulatory Domain</p> <p>3.10.4.19 30 units Outdoor Access Access Point</p> <p>3.10.4.20 2 units Wireless Controller Copper Uplink</p> <p>3.10.4.21 2 units Wireless Controller</p> <p>3.10.4.22 34 units 10GBASE-Legacy Reduced Small Form Factor Module, Enterprise Class</p> <p>3.10.4.23 2 licenses Solution Support 8X5XNBD Spine Switch, 36p 40/100G QSFP28</p>

REFERENCE	QUERIES	AMMENDMENTS/ CLARIFICATIONS
		<p>3.10.4.24 — 2 licenses solution Support 8X5XNBD Leaf Switch 48p 1/10/25G, 6p 40/100G;</p> <p>3.10.4.25 — Licenses, Software Subscription, and After Sales Warranty Services</p> <p>3.10.4.26 — 10 pax Administration's Training</p> <p>3.10.4.27 — Data Center Switches Latest Operating System Software</p> <p>3.10.4.28 — Data Center Switch Fan, 35CFM, port side exhaust airflow with Electrically Erasable Programmable Read-only Memory (EEPROM)</p> <p>3.10.4.29 — Power Cord Jumper, C13-C14 Connectors, 2 Meter Length</p> <p>3.10.4.30 — 40GBASE-SR4 QSFP Transceiver Module, MPO Conn, Enterprise Class</p> <p>3.10.4.31 — 3K/9K Fixed Accessory Kit, IRU front and rear removal</p> <p>3.10.4.32 — NEBs AC 650W PSU Port Side Exhaust</p> <p>3.10.4.33 — Network Plug-n-Play Connect for zero touch device deployment</p> <p>3.10.4.34 — North America AC Type A Power Cable</p> <p>3.10.4.35 — 50CM Type 4 Stacking Cable</p> <p>3.10.4.36 — 715W AC 80+ platinum Config 1 Power Supply</p> <p>3.10.4.37 — Switch Stack Power Cable 30 cm</p> <p>3.10.4.38 — No SSD Card Selected</p> <p>3.10.4.39 — AC Power Cord, Type C5, US, Canada</p> <p>3.10.4.40 — Data Center Switch Network Module Blank Module</p> <p>3.10.4.41 — Blank Stack Module</p> <p>3.10.4.42 — Vertical pole/wall mounting kit for Access Points</p> <p>3.10.4.43 — 2.4GHz 6dBi/ 5GHz 8dBi Dual Band Omni Antenna N Connector</p> <p>3.10.4.44 — 802.11 AP Low Profile Mounting Bracket</p> <p>3.10.4.45 — Ceiling Grid Clip for Access Points & Cellular Gateways Recessed</p> <p>3.10.4.46 — Wireless Controller Rack Mount Tray</p> <p>3.10.4.47 — Wireless Controller Power Supply</p> <p>3.10.4.48 — 1 lot Project Management Services</p> <p>3.10.4. 1 lot Project Management Services</p> <p>3.10.4.49 — 1 lot Installation and Configuration</p> <p>3.10.5. 1 lot Installation and Configuration</p> <p>3.10.4.50 — 3.10.6. 1 lot Deployment and implementation services</p> <p>3.10.6. 1 lot Deployment and implementation services</p> <p>3.10.4.51 — 3.10.7. Two (2) years warranty and support services</p> <p>3.10.7. Two (2) years warranty and support services</p>

REFERENCE	QUERIES	AMMENDMENTS/ CLARIFICATIONS
3. 11 Network Security System 3.11.1.13. NGFW Features and Functionalities (Applies to NGFW in all locations)	Please clarify the following: <ul style="list-style-type: none"> • Performance requirement <ul style="list-style-type: none"> - Threat protection throughput in Mbps/Gbps • Interface requirement: 1G or 10G • How many and what types of servers need to be protected • No. of ISPs & bandwidth 	<ul style="list-style-type: none"> • Performance requirement <ul style="list-style-type: none"> - Threat protection throughput in 28 Gbps • Interface requirement is 10G • All applications, data/storage, CCTV, and back-up servers need to be protected • 2 1Gbps Internet Exchange capacity from a reputable ISP (Internet Service provider)
3. 11 Network Security System 3.11.2. Intrusion Prevention System (IPS)	Please clarify the following: <ul style="list-style-type: none"> • Is this part of the NGFW? • Please confirm if HA 	<ul style="list-style-type: none"> • Yes, this is part of the NGFW. • Yes, the design must be High Availability Configuration.
3. 11 Network Security System 3.11.3. Web Application Firewall (WAF)	Please clarify the following: <ul style="list-style-type: none"> • Can this be part of NGFW? • How many web app/s needs to be protected? • Projected Network Throughput within 3 or 5 yrs? • Estimated number of concurrent connections per second? Estimated no of users? • Connectivity (copper or fiber?) <ul style="list-style-type: none"> - if fiber: 1G, 10G, or 40G • Please confirm if HA 	Kindly refer to specifications provided under this section in the PBD.
3. 11 Network Security System 3.11.4. Endpoint Detection and Response (EDR)	Please clarify the following: <ul style="list-style-type: none"> • OS running in your endpoints (Ex: Win10) 	The following are the OS running in EVSU: Win10, Win11, IOS, Android, Linux.
3. 11 Network Security System 3.11.5.1. Security Information and Event Management (SIEM)	Please clarify the following: <ul style="list-style-type: none"> • No. of devices to be monitored • Total/estimated throughput (logs/second, logs/day) 	Per Sec. 3.11.5.1.1. The solution must be able to collect amounts of data without limiting the number of devices to collect from.
3. 11 Network Security System 3.11.6. Security Orchestration, Automation, and Response (SOAR)	<ul style="list-style-type: none"> • No. of users (Can be named or concurrent) • User count that requires to simultaneously log in at a given point in time 	Kindly refer to specifications provided under this section in the PBD.

REFERENCE	QUERIES	AMMENDMENTS/ CLARIFICATIONS
<p>3.13 Data Center Compute Nodes</p> <p>3.13.5 Supply delivery and installation of Data Center Compute Nodes and must at least consist of the following:</p> <p><i>3.13.5.1 to 3.13.5.89 (Breakdown of requirements)</i></p>	<p>We understand that in the Terms of Reference (TOR) it should not be brand specific, however, it was found in the breakdown of requirements in 3.13.5 that EVSU is leaning towards some brands.</p> <p>Further, the following are branded Switches/UPS specifications that were included on the breakdown of server requirements:</p> <p>3.13.5.23 2 units MDS 9100V 500W Port Side Exhaust Power Supply Unit (PSU) - Cisco</p> <p>3.13.5.33 2 licenses MDS 9124V 64G FC switch 8 port upgrade licenses - Cisco</p> <p>3.13.5.34 1 license MDS 9128V Nexus Operating System (NX-OS) version 9.3.1 - Cisco</p> <p>There are also items identified as redundant:</p> <p>3.13.5.31 6 licenses NVIDIA General Repository for Interaction Datasets (GRID) Software OPT-OUT</p> <p>3.13.5.32 6 licenses NVIDIA General Repository for Interaction Datasets (GRID) Software OPT-OUT</p> <p>3.13.5.13 2 units Windows Server 2022 Data Center (16 Cores/Unlimited Virtual Machines)</p> <p>3.13.5.84 2 units Windows Server 2022 Data Center (16Cores/Unlim VM) Rec Media DVD Only</p>	<p>3.13.5 Supply delivery and installation of Data Center Compute Nodes and must at least consist of the following:</p> <p>3.13.5.1 2 units Intelligent Modular Uninterruptable Power Supply 250kva</p> <p>3.13.5.2 4 units Power Module 50kva</p> <p>3.13.5.3 1 units BCB Box, 250kva</p> <p>3.13.5.4 4 sets CRV4 Thermal Management Solutions</p> <p>3.13.5.5 20 10 units Server Rack, 42U x 600 width x 1200-dimension, front single & rear split mesh door, with side panels, RAL7021 black, flat pack into 5 cartons</p> <p>3.13.5.6 1 unit RDU THUB Sensor Extension Module</p> <p>3.13.5.7 2 sets IRM TIDD 3rd Party Device Driver Development (Modbus /SNMP)</p> <p>3.13.5.8 4 units M6 Rack, Blade Main Logic Board</p> <p>3.13.5.9 7 units M6 Rack without CPU memory drive 1U with Small Form Factor 10Hard Disk Drive backplane</p> <p>3.13.5.10 3.13.5.6 4 units Integrated Management Controller</p> <p>3.13.5.11 7 units 12G Serial Attached SCSI (SAS) Redundant Array of Independent Disks (RAID) Controller with 4GB Flash Backed Write Cache (FBWC) (16 drive) with 1U bracket</p> <p>3.13.5.12 8 units QLogic 2x32 Gigabit Fibre Channel (GFC) Gen 6 Enhanced Peripheral Component Interconnect Express (PCIe) Host Bus Adapter (HBA)</p> <p>3.13.5.13 2 units Windows Server 2022 Data Center (16 Cores/Unlimited Virtual Machines)</p> <p>3.13.5.14 13 units Advanced Micro Devices (AMD) 3.0GHz 7313 155W 16C/128MB Cache Double Data Rate 4th Generation (DDR4) 3200MHz</p> <p>3.13.5.15 7 units Voice Interface Card (VIC) 15428 Quad Port 10 25 50G MLOM</p> <p>3.13.5.16 66 units 32GB Registered Dual Inline Memory Module (RDIMM) SRx4 3200 (16Gb)</p> <p>3.13.5.17 4 units 240GB 2.5in M.2 Serial Advanced Technology Attachment (SATA) Micron G1 Solid State Drive (SSD)</p> <p>3.13.5.18 12 units 1.9TB 2.5 inch Enterprise Value 6G Serial Advanced Technology Attachment (SATA) Solid State Drive (SSD)</p> <p>3.13.5.19 6 units NVIDIA T4 Peripheral Component Interconnect Express (PCIe) 75W 16GB</p> <p>3.13.5.20 14 units 25 Gigabit Ethernet Small Form Factor Pluggable (25GBASE-SR SFP) Module</p> <p>3.13.5.21 14 units 3.8TB 2.5in Enterprise Value 6G Serial Advanced Technology Attachment (SATA) Micron G1 Solid State Drive (SSD)</p> <p>3.13.5.22 20 sets Redetec with Point detectors: Novec1230 suppression for 3.0m³</p> <p>3.13.5.23 2 units MDS 9100V 500W Port Side Exhaust Power Supply Unit (PSU)</p>

REFERENCE	QUERIES	AMMENDMENTS/ CLARIFICATIONS
	<p>In addition, may we be clarified on the required quantity for the CPU of the Bare Metal Servers? As indicated, the end user's required quantity is thirteen (13), however, the no. of BareMetal servers to be supplied is only two (2) with dual CPU (64-cores) each. Hence, will only require 4 units of CPUs, not 13.</p> <p>3.13.5.14 13 units Advanced Micro Devices (AMD) 3.0GHz 7313 155W 16C/128MB Cache Double Data Rate 4th Generation (DDR4) 3200MHz</p> <p>Overall, we have observed that the provided breakdown of server requirements points to specific brands such as Cisco, Redetec, Windows, Red Hat Linux, Vision, and Vertiv. Also, we have observed that some of the requirements were misplaced (UPS and Switches).</p> <p>In this regard, may we kindly request the EVSU BAC to remove items 3.13.5.1 to 3.13.5.89 and replace it with brand agnostic general specifications.</p>	<p>3.13.5.241 license IRM 3D—Custom 3D Graphic Layout Software 3.13.5.258 licenses for annual subscription Solution Support M6 Rack w/o CPU, memory, drive, IU w for 3-years subscription 3.13.5.267 licenses Trusted Platform Module 2.0 (FIPS 140-2 Compliant) 3.13.5.272 for annual licenses ISV 24X7 Windows Server 2022 Data Center (16 Core) for 3-year subscription 3.13.5.2848 for annual licenses ISV 24X7 Windows Server 2022 Data Center—Additional for 3-year subscription 3.13.5.295 licenses Red Hat Enterprise Linux for Virtual Datacenters (1-2 CPU, Unlim VN) 3-year Support and Subscription required 3.13.5.305 licenses Red Hat Enterprise Linux for Virtual Datacenters Premium 24x7—3-year Support 3.13.5.316 licenses NVIDIA General Repository for Interaction Datasets (GRID) Software OPT-OUT 3.13.5.326 licenses NVIDIA General Repository for Interaction Datasets (GRID) Software OPT-OUT 3.13.5.332 licenses MDS 9124V 64G FC switch 8-port upgrade licenses 3.13.5.341 license MDS 9128V Nexus Operating System (NX-OS) version 9.3.1 3.13.5.351 license MDS Advantage Subscription M9100V 3-year subscription 3.13.5.361 license Embedded Solution support for MDS 3.13.5.3748 licenses Windows Server 2022 Data Center—Additional 2 Cores 3.13.5.383 yearly subscription Yearly extended warranty for Redetec with Point Detectors: Novee 1230 suppression for 3.0m³ 3.13.5.3912 sets Temperature Sensor Cable Set 3.13.5.402 pcs Dome IP Camera mounting bracket 3.13.5.4127 pcs Bottom plate for server rack, 600*1200 3.13.5.4227 pcs 600mm W power shielding Trough, Tool less mounting on Top Panel, 1 piece 3.13.5.4327 pcs 600mm W data shielding partition, Tool less mounting on Top Panel, set of 2 pieces 3.13.5.44640 pcs IU Toolless Mounting Metal Blank Panel 3.13.5.4540 pcs Geist Monitored Unit Level PDU, Vertical, 230V/32A, IEC603091P+N+E, 3m Power Cord, 20xC13, 4xC19, U-Lock Outlets, Black 3.13.5.462 pcs 120mm width cross row overhead cable bridge for power cables 3.13.5.472 pcs 300mm width cross row overhead cable bridge for data cables 3.13.5.4828 pcs 600mm width rack top mount cable channel 3.13.5.4974 pcs Temperature and Humidity Sensor 3.13.5.501 pc 8COM extension card 3.13.5.512 pcs ECM Input and Output Switch Sub Assembly 3.13.5.522 card IS-Unity DP-SNMP/Web Card 3.13.5.532 pcs 15m Parallel cable for EXM, APM (250/400/600)</p>

REFERENCE	QUERIES	AMMENDMENTS/ CLARIFICATIONS
		<p>3.13.5.5412 units Temperature Sensor 3.13.5.554 units IRMS01T Temperature Sensor 3.13.5.561 pc 8 Digital Input Analog Input extension card 3.13.5.571 pc 8 Digital Output Analog Output extension card 3.13.5.581 pc IP Door Controller / CHD806-1U 3.13.5.592 pcs Optical Fingerprint Reader 3.13.5.601 pc Fingerprint Release Device—USB 3.13.5.612 pcs EP68—Exit Button 3.13.5.622 licenses RDU-A G2 or RDU501 License Extension—1 Device (Maximum order of 16 PER Device RDU-A G2, 32 per device (RDU501)) 3.13.5.632 licenses, node Basic Support for DCM 3.13.5.647 licenses Integrated Management Controller (IMC) Supervisor—Advanced 3.13.5.657 licenses Central Per Server 3.13.5.664 licenses Intersight Software as a Service (SaaS) 3.13.5.6712 licenses Intersight Software as a Service (SaaS)—Advantage 3.13.5.6812 units Vision 6FM200-X, 200AH, 12V VRLA Batteries 3.13.5.694 units Battery Cabinet 3.13.5.704 units Battery Breaker 3.13.5.714 units Blanking Panel 3.13.5.727 units Ball Bearing Rail Kit for M6 Rack Servers 3.13.5.7324 units M5 Small Form Factor drive blanking panel 3.13.5.74158 units Dual In-line Memory Module (DIMM) Blanks 3.13.5.757 units M6 Supercap 3.13.5.767 units M6 1U/2U Super Cap cable 3.13.5.7713 units Heatsink 1U Small Form Factor M6 3.13.5.787 units M6 Riser2 HH; x16; LPBkt; (CPU2) 3.13.5.797 units M6 Riser3 HH; x16; LPBkt; (CPU2) 3.13.5.807 units 600GB Serial Attached SCSI (SAS) 12Gb 10K Revolutions Per Minute (RPM) 4K Small Form Factor (SFF) Internal Hard Drive 3.13.5.8114 units 1600W Alternating Current (AC) Power Supply for Rack Server 3.13.5.8214 units Power Cord Jumper, C13-C14 Connectors, 2 Meter Length 3.13.5.832 units Cabinet Jumper Power Cord, 250 VAC 13A, C14-C15 Connectors 3.13.5.842 units Windows Server 2022 Data Center (16Cores/Unlim VM) Rec Media DVD Only 3.13.5.852 units Boot optimized M.2 Redundant Array of Independent Disks (RAID) controller 3.13.5.864 units 480GB 2.5-inch Enterprise Value 6G Serial Advanced Technology Attachment Solid State Drive (SATA SSD) 3.13.5.8724 units 32 Gbps Fibre Channel SW SFP+, LC 3.13.5.884 units MDS 9132 Fan Tray Port Side Exhaust</p>

REFERENCE	QUERIES	AMMENDMENTS/ CLARIFICATIONS
		<p>3.13.5.891 unit MDS 9124V Accessory Kit 3.13.5.9020 units Rackmount kit 3.13.5.91 3.13.5.7 1 lot Project Management Services 3.13.5.92 3.13.5.8 1 lot Installation and Configuration 3.13.5.93 3.13.5.9 1 lot Deployment and implementation services 3.13.5.94 3.13.5.10 Two (2) years warranty and support services</p>
<p>3.15 Data Center Back-Up System</p> <p>3.15.6. The solution must support an average 55:1 data deduplication rate</p>	<p>The 55:1 deduplication is not a standard on all types of data undergoing the deduplication process and cannot be guaranteed.</p> <p>We would like to propose that the requirement be considered into “Solution must have deduplication capabilities with an average of 10:1 ratio.” This is the average capability of deduplication solution technologies available today.</p>	<p>This item shall be amended as follows:</p> <p>3.15.6. The solution must support an average 55:1 10:1 data deduplication rate.</p>
<p>3.15 Data Center Back-Up System</p>	<p>Does EB Rm 204 have cooling equipment for the data center back-up system appliance to be supplied? does it need to be separated from the new data center?</p>	<p>Yes.</p>
<p>3.16 University Information System</p>		<p>3.16.7.1.1.13. Solution must allow users to create PPMP that can generate a consolidated APP and reference for the items in the PR.</p>
<p>3.22 Video Wall Display (Elec&onic Billboard)</p> <p>3.22.3.5 Brightness: At least 6000 NITs</p>	<p>As per our coordination with several Technical Engineers of Electronic Billboard suppliers, the higher the brightness requirement, which in this case is at least 6,000 Nits, the higher the power consumption will be. This condition will have a negative impact or have a direct disadvantage on the operating temperature, which results in lower capabilities that can be delivered by the Video Wall Display.</p> <p>With this, can the EVSU consider updating the brightness requirement to "At least 4000 NITS"?</p>	<p>3.22.3.5 Brightness: At least 6000 4000 NITs</p>

REFERENCE	QUERIES	AMMENDMENTS/ CLARIFICATIONS
<p>3.23. Electrical Works and Power Back-Up System</p> <p>3.23.1. Design and build of a power shed facility sufficient to house standby generators with synchronizer system sufficient to supply the demand load and future load of the whole university. This includes major electrical equipment such as 2 units of 3-phase WYE to DELTA Dry Type Power Transformer, and switchgears that will supply the entire campus.</p> <p>3.23.9 Cable supply and labor works connected to the different buildings (Refer to ANNEX H) supported by the backup system shall be through the account of the winning bidder.</p>	<p>Our understanding is the Power Shed shall be sized and planned sufficiently to house future loads with corresponding equipment, and that the Day 1 equipment as defined in the Bid Documents, supply power to the 17 Buildings as listed in “Annex H” of the bid documents. Kindly confirm our understanding.</p>	<p>The winning bidder may utilize the existing electrical materials to supply power to the updated list of buildings, to wit:</p> <p>Section IX. Bidding Forms <u>ANNEX H</u></p> <p style="text-align: center;">LIST OF BUILDINGS</p> <p>Supply power to the following buildings in the Eastern Visayas State University Main Campus:</p> <ul style="list-style-type: none"> I. Women’s Technology Building II. New COBE Building III. Graduate School Building IV. Cafeteria V. Food Innovation Center VI. Shared Service Facility VII. ORDEX Building VIII. Academic Building IX. Wood Working/New Administration Building X. SASO/SSG Student Center Building XI. Learning Commons XII. Science Building XIII. EVSUFA Balay XIV. Asia Pacific XV. Water Supply System XVI. Innovation Hub XVII. EVSU Multi-Purpose Cooperative
<p>3.25. Warranty and Support Services</p> <p>3.25.1. The university requires warranty, support, and maintenance services, which shall be valid for within the specified duration as stated per component in Section 3.0 of this document. The winning bidder must include the following, at a minimum, among other terms and conditions of the warranty and support contract:</p> <p>3.25.1.1 Break-fix provision</p> <p>3.25.1.2 Replacement of Defective Parts or Units whichever is applicable</p>	<p>May we know what equipment are covered under 3.25.1.1 to 3.25.1.4?</p> <p>Considering not all equipment can be subjected to the said activities/provisions, may we recommend that this will be applicable only for Data Center UPS and Precision Cooling Units, taking into account their critical nature in the operation of the Data Center Facility.</p>	<p>3.25. Warranty and Support Services</p> <p>3.25.1. The university requires warranty, support, and maintenance services for major equipment such as, but not limited to, UPS, Switches, Servers, Access Points, WLAN Controllers, Cooling Units, Facial Recognition System, which shall be valid for within the specified duration as stated per component in Section 3.0 of this document. The winning bidder must include the following, at a minimum, among other terms and conditions of the warranty and support contract:</p> <p>3.25.1.5 Break-fix provision</p> <p>3.25.1.6 Replacement of Defective Parts or Units whichever is applicable</p> <p>3.25.1.7 Provision of Service Units (not more than 2 days upon completion of the diagnosis) in cases where the supplied equipment is/are pulled out from the facility or would require replacement.</p>

REFERENCE	QUERIES	AMMENDMENTS/ CLARIFICATIONS
<p>3.25.1.3 Provision of Service Units (not more than 2 days upon completion of the diagnosis) in cases where the supplied equipment is/are pulled out from the facility or would require replacement.</p> <p>3.25.1.4 Periodic Preventive Maintenance Services (PMS) compliant with the manufacturer's PMS specifications. with the manufacturer's PMS specifications.</p>		<p>3.25.1.8 Periodic Preventive Maintenance Services (PMS) compliant with the manufacturer's PMS specifications. with the manufacturer's PMS specifications.</p>
<p>Section VIII. Checklist of Technical and Financial Documents (Item No. 7 Conformity with the Technical Specifications)</p> <p>iii. Certification that the personnel to be deployed is trained and accredited of the product to be supplied (with attachment of the personnel's profile, ID, etc.)</p>	<p>Can EVSU consider this requirement to be applicable only for major configurable requirements, which are Desktop, Network, and Servers?</p> <p>For minor and non-configurable equipment, International Manufacturers and Distributors may not issue such certification.</p>	<p>This item shall be amended as follows:</p> <p>Section VIII. Checklist of Technical and Financial Documents (Item No. 7 Conformity with the Technical Specifications)</p> <p>iii. Certification that the personnel to be deployed is trained and accredited of the product only for major configurable requirements such as, but not limited to, Servers, Switches, Firewall, UPS, to be supplied (with attachment of the personnel's profile, ID, etc.)</p>
<p>Section VIII. Checklist of Technical and Financial Documents (Item No. 4 Philippine Contractors Accreditation Board (PCAB) License; OR Special PCAB License in case of Joint Ventures)</p>	<p>In relation to GPPB Resolution No. 15-2020, may we be allowed to declare our subcontractor and submit the required project requirements related to the design and build component during the project implementation stage?</p> <p>Considering that (a) this is a Procurement for Goods and Services with civil works component not exceeding 20% of the project cost (b) the interested and expected bidder/s is/are not into the business of general construction and building but in the supply of ICT products for installation in the Smart Campus facility, and (c) there is a standard and uniform checklist for Procurement of Goods under the 6th Edition of Philippine Bidding Documents enumerating the eligibility requirements of which the</p>	<p>Yes.</p> <p>This is a mixed procurement project. The Procuring Entity is allowed to add requirements it deems necessary aside from the listed minimum requirements in the PBD. PCAB for SF-CF will be required from bidders as this procurement pertains Communication Facilities.</p>

REFERENCE	QUERIES	AMMENDMENTS/ CLARIFICATIONS
	<p>Procuring Entity cannot add or remove, is this requirement still valid?</p> <p>While it has been the practice of DPWH and other infra-agencies to examine the PCAB license of subcontractors when it comes to mixed procurement, such practice is not necessarily binding to other agencies whose projects are not principally for procurement of infrastructure service. In fact, this practice has been amended with the approval of GPPB Resolution No. 15-2020 on “Adoption of the 6th Edition of the Philippine Bidding Documents for the Procurement of Goods and Infrastructure Projects and related Amendments in the 2016 Revised IRR of RA 9184 and Associated Issuances”, which necessarily amends the Government Procurement Manual Vol. 2 on Manual of Procedures for the Procurement of Goods, where it says:</p> <p>“The bidder may identify the subcontractor to whom a portion of the Works will be subcontracted AT ANY STAGE OF THE BIDDING PROCESS OR DURING CONTRACT IMPLEMENTATION. If the bidder opts to disclose the name of the subcontractor during bid submission, the bidder shall include the required documents as part of the technical components of the bid. A subcontractor that is identified during contract implementation must comply with the eligibility criteria and documentary requirements.”</p> <p>Clearly, the inclusion in the expanded Checklist for the submission of eligibility criteria and documentary requirements contradicts the above cited clause in the Manual of Procedure which gave the Bidder</p>	

REFERENCE	QUERIES	AMMENDMENTS/ CLARIFICATIONS
	<p>the option to either disclose his subcontractor during the bidding process or only after award and upon contract implementation.</p> <p>Thus, it is requested that such requirement in Items #4 and 7(h) shall be removed in the bidding documents as it pertains only to requirements for Procurement of Infra Projects which is not the main purpose of the project. It will only add to the complexities of the bid preparation as it already is. Submission can be made during contract implementation.</p>	
Price Schedule Form under Annex G	For purposes of bid submission, does the “Particulars” pertain to the Components of the project?	The “Particulars” pertain to each item (refer to Section VI. Schedule of Requirements) and corresponding sub-items of the project which the bidder shall state in their Price Schedule.
	Is it true that there is an additional charge for outside contractors of Tacloban? Has this been considered in the costing?	No.

All statements and formats referring to this clause should be amended/corrected accordingly.

For guidance and information of all concerned.

For further information, please refer to:

VINCENT B. CABANTOC

Head, BAC Secretariat

CP No. 0953-355-7046 - TM

Email Add: evsu.bacsecretariat@evsu.edu.ph

Noted:

(SGD.)

BENEDICTO T. MILITANTE, JR., Ph.D., J.D.

Vice President for Administration & Finance

Chairperson, Bids and Awards Committee

ANNEX “A”

GUIDELINES FOR ELECTRONIC SUBMISSION OF BIDS

1. Each documentary requirement shall be scanned into a printable Portable Document Format (PDF).
2. The documentary requirements shall be segregated and labelled according to the type of document for prompt identification: e.g., PhilGEPS Certificate of Registration (Platinum) – PhilGEPS
3. A two-folder system will be utilized. The first folder contains the requirements of the Technical Component checklist as presented under Section VIII and shall be labeled “**TECHNICAL COMPONENT**”. The second folder contains the requirements of the Financial Component checklist and is marked “**FINANCIAL COMPONENT**”.
4. Each folder shall be compressed in Zip, RAR or 7z format with password protection. Submitted bidding documents that are not in compressed archive format and are not password protected, will be automatically rejected.
5. The password for accessing the file shall be disclosed by the Bidders during the submission of the bid which may be done in person or face-to-face through videoconferencing, webcasting, e-mail or similar technology.
6. Bidders must submit the 2 compressed folders through e-mail to evsu.bacsecretariat@evsu.edu.ph at any time before October 27, 2023, 10:00 A.M.
7. For further information, please refer to:

For guidance and information of all concerned.

For further information, please refer to:

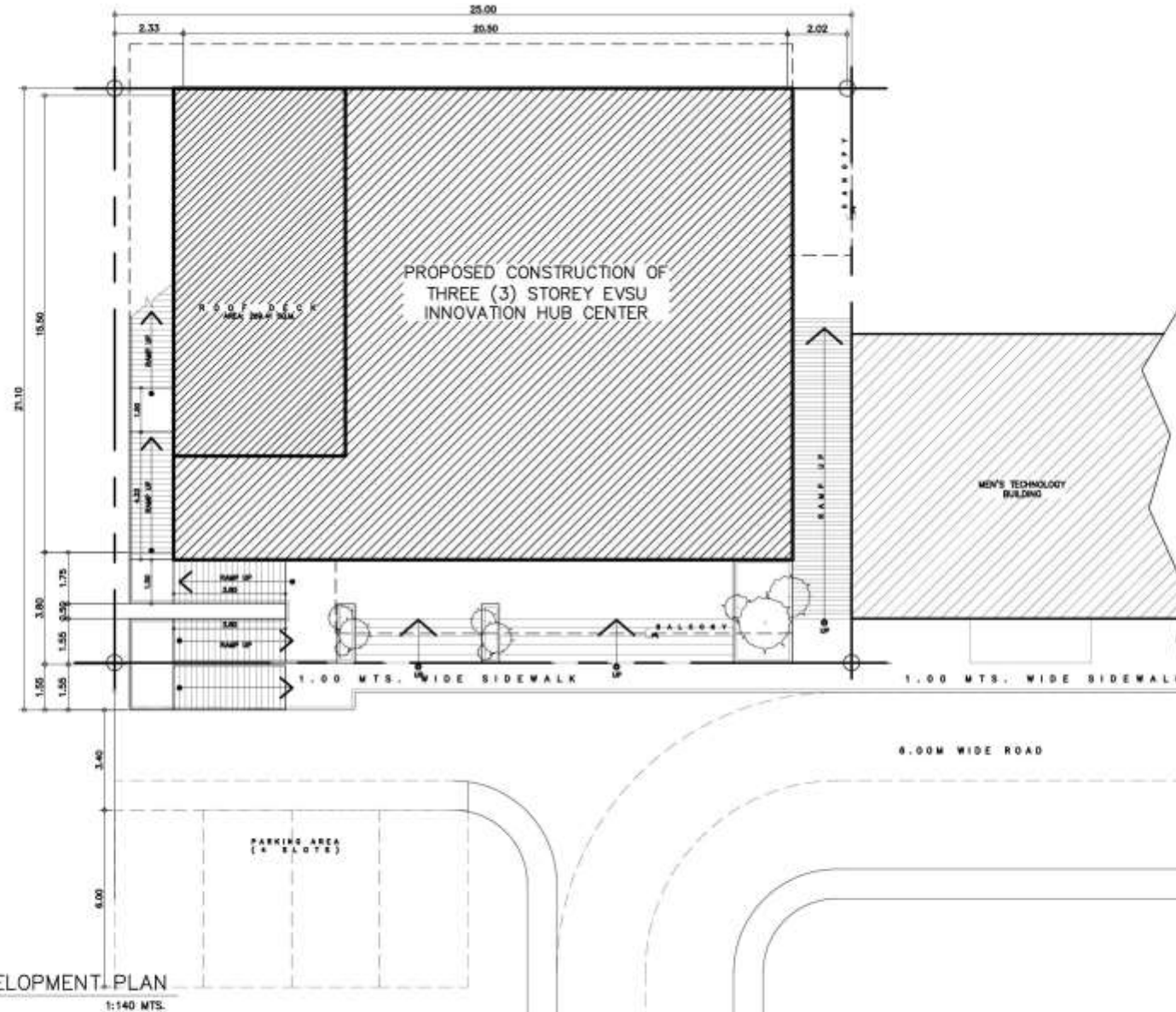
VINCENT B. CABANTOC

Head, BAC Secretariat

CP No. 0953-355-7046 - TM

Email Add: evsu.bacsecretariat@evsu.edu.ph

ANNEX "B"

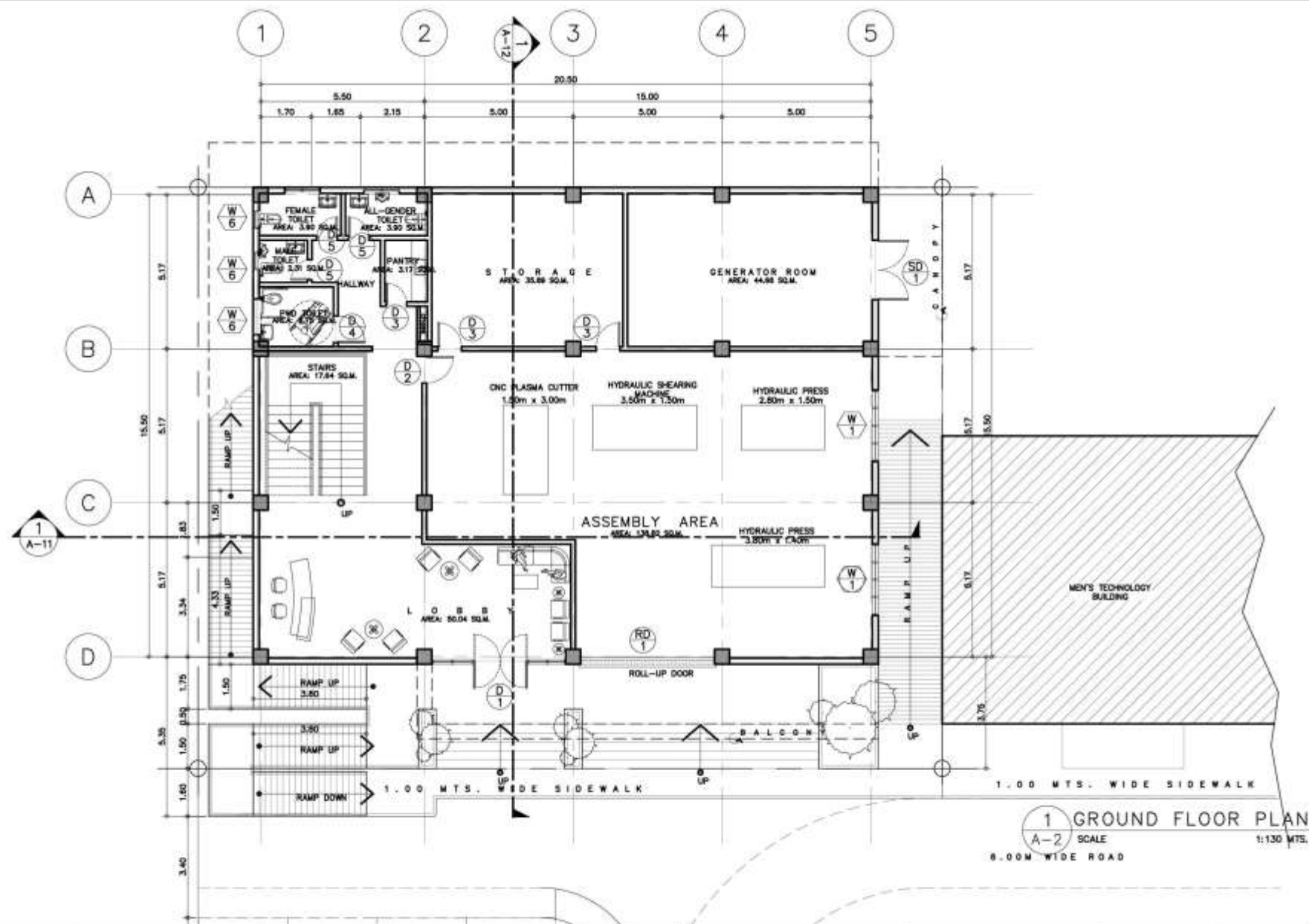


1 SITE DEVELOPMENT PLAN
A-2 SCALE 1:140 MTS.




PPIDO (PHYSICAL PLANNING AND INFRASTRUCTURE DEVELOPMENT OFFICE)	ARCHITECT: AR. BERNIE G. TUDIO, UAP HEAD, PPIDO	ALL WORK DRAWINGS AND SPECIFICATION SHALL BE SIGNED, STAMPED AND SEALED AS REQUIREMENTS OF SERVICE. ARE THE PROPERTY AND DOCUMENT OF THE ARCHITECT. MASTERED THE SUBJECT FOR WHICH THEY ARE MADE IS EXCLUDED OR NOT. IT SHALL BE UNLAWFUL FOR ANY PERSON WITHOUT THE WRITTEN CONSENT OF THE ARCHITECT TO DUPLICATE OR MAKE COPIES OF THIS DOCUMENT OF THE WHOLE OR IN PART.	PROJECT TITLE: SMART CAMPUS ENHANCEMENT PROGRAM (CONSTRUCTION OF THREE (3) STOREY INNOVATION HUB BUILDING)	RECOMMENDING APPROVAL: PROF. CHRISTOPHER C. BACUNGAN, MAECON Director, PPDO	APPROVED BY: DR. DENNIS C. DE PAZ University President	SHEET CONTENT: SITE DEVELOPMENT PLAN	PROJECT ID NO.	SHEET NO.
	PREC. NO. DT. ISS. PDR. NO. PL. ISS.		LOCATION: EVSU-MAIN CAMPUS, TAGLARAN CITY	REV. NO.: _____ DATE SUBMITTED: _____	A 2 25			

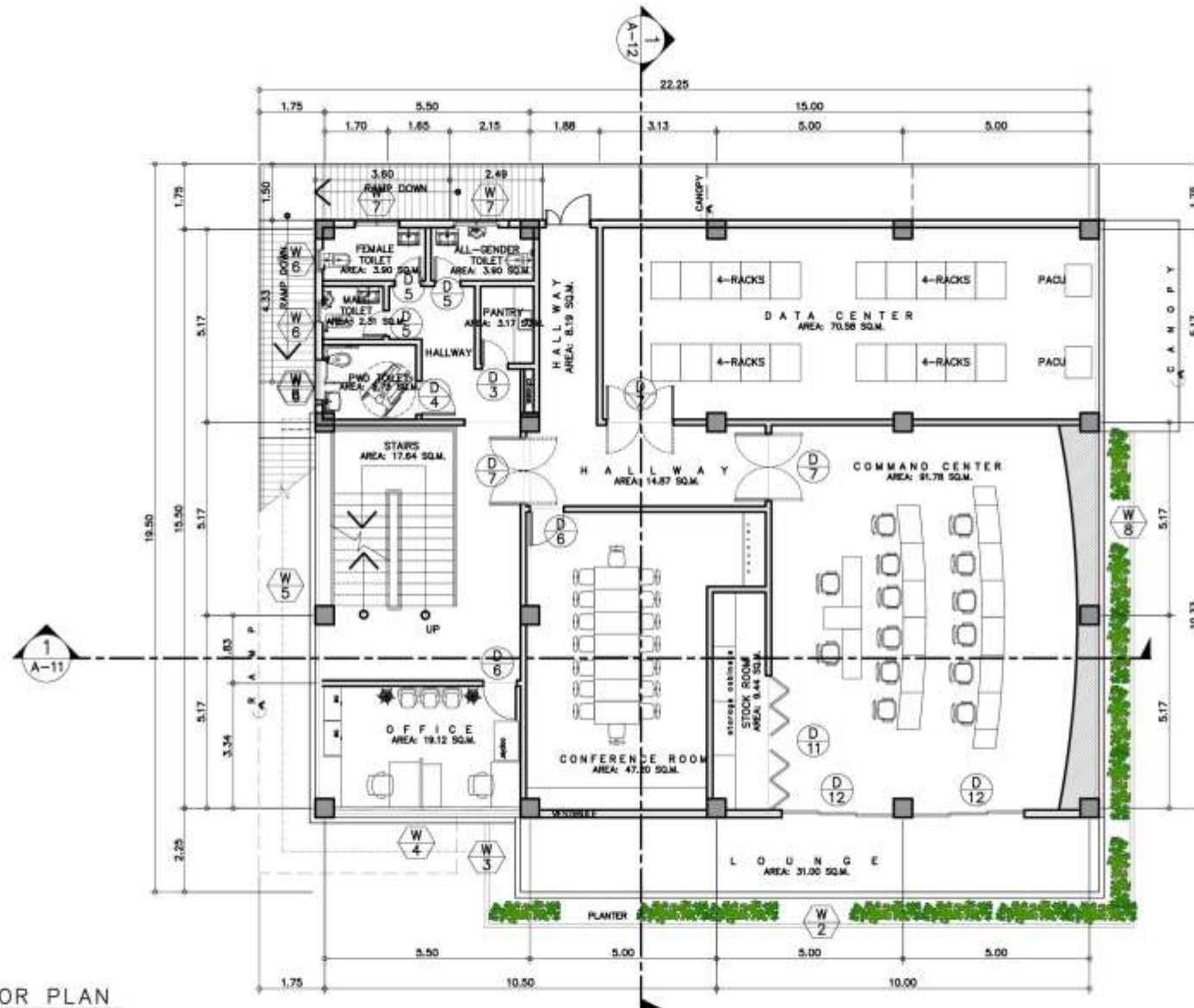
ANNEX "B"



1 GROUND FLOOR PLAN
A-2 SCALE
1:130 MTS.
8.00M WIDE ROAD

	PREPARED BY: PPDO (PHYSICAL PLANT AND INFRASTRUCTURE DEVELOPMENT OFFICE)	ARCHITECT: AR. BERNE G. TUDJO, UAP HEAD, PPDO	P.A. 9288 DRAWINGS AND SPECIFICATION DULY SIGNED, STAMPED AND SEALED, AS INSTRUMENTS OF SERVICE, ARE THE PROPERTY AND DOCUMENT OF THE ARCHITECT. WHETHER THE OBJECT FOR WHICH THEY ARE MADE IS EXECUTED OR NOT, IT SHALL BE UNLAWFUL FOR ANY PERSON WITHOUT THE WRITTEN CONSENT OF THE ARCHITECT TO REPRODUCE OR MAKE COPIES OF THIS DOCUMENT OR OF THE WHOLE OR A PART.	PROJECT TITLE: SMART CAMPUS ENHANCEMENT PROGRAM (CONSTRUCTION OF THREE (3) STOREY INNOVATION HUB BUILDING)	RECOMMENDING APPROVAL: PROF. CHRISTOPHER C. BACUNGAN, MAECON Director, PPDO	APPROVED BY: DR. DENNIS C. DE PAZ University President	SHEET CONTENT: GROUND FLOOR PLAN	PROJECT ID NO.	SHEET NO.
	PRE. NO. DT. SS. PPL. NO.	DT. SS. PL. SS.	LOCATION: EYSU-MAIN CAMPUS, TAGLISAN CITY	REV. NO.: _____ DATE SUBMITTED: _____	A 3/25				

ANNEX “B”



1 SECOND FLOOR PLAN
A-4 SCALE 1:120 MTS.



PREPARED BY:	ARCHITECT:
PPIDO (PHYSICAL PLANT AND INFRASTRUCTURE DEVELOPMENT OFFICE)	AR. BERNIE G. TUDIO, UAP HEAD, PPIDO
PRC NO.	GT. ISS.
PTL NO.	PL. ISS.

PLANS, SPECIFICATIONS, DRAWINGS AND SPECIFICATIONS DULY SIGNED, STAMPED AND SEALED AS INSTRUMENTS OF SERVICE, AND THE PROPERTY AND DOCUMENT OF THE ARCHITECT. WHICHEVER THE SUBJECT FOR WHICH THEY ARE MADE IS ENCLOSED OR NOT, IT SHALL BE UNLAWFUL FOR ANY PERSON WITHOUT THE WRITTEN CONSENT OF THE ARCHITECT TO DUPLICATE OR MAKE COPIES OF THIS DOCUMENT OF THE WHOLE OR IN PART.

PROJECT TITLE:
SMART CAMPUS ENHANCEMENT PROGRAM (CONSTRUCTION OF THREE (3) STOREY INNOVATION HUB BUILDING)
LOCATION: EVSU-MAIN CAMPUS, TAGLIDIAN CITY

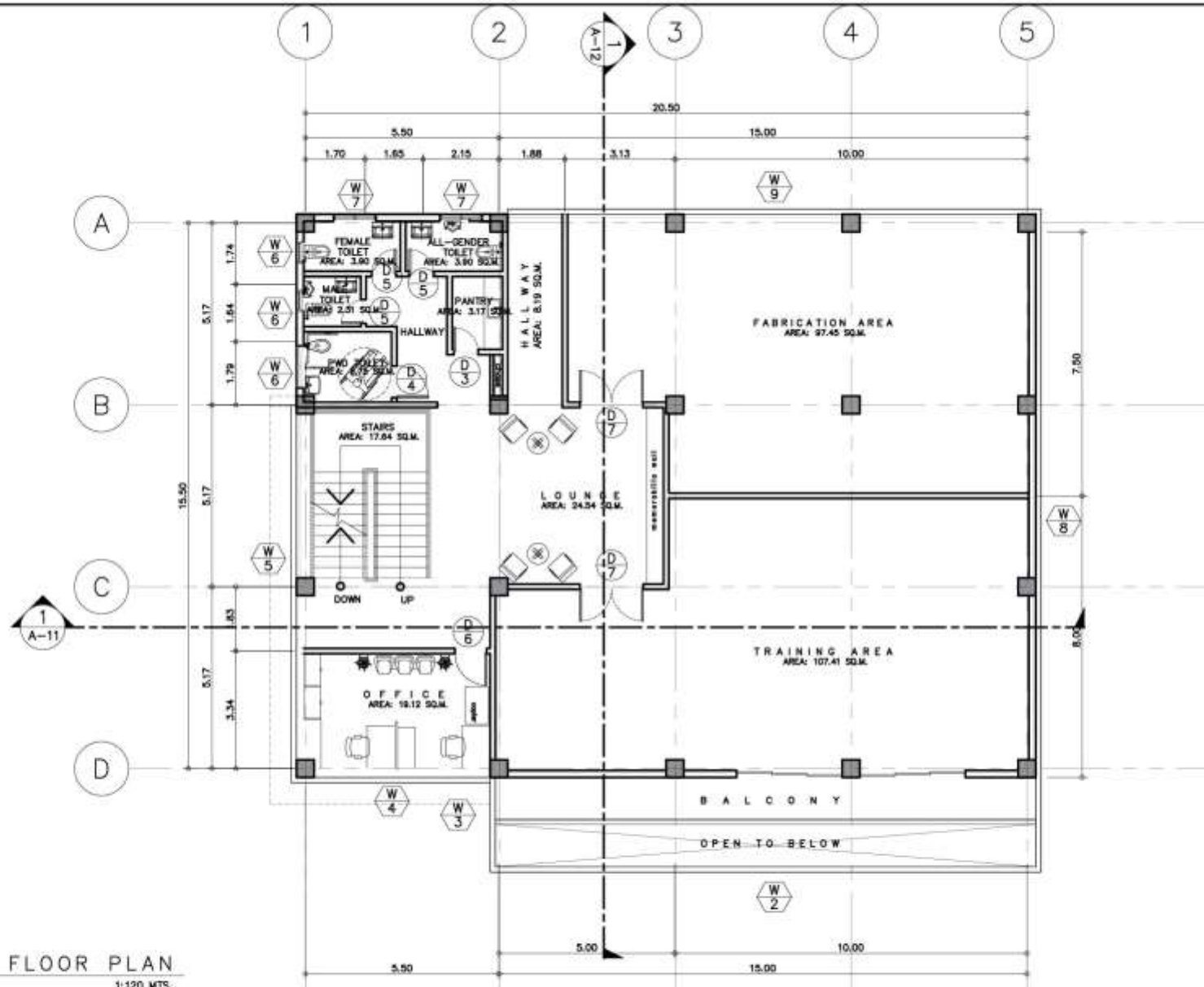
RECOMMENDING APPROVAL:
PROF. CHRISTOPHER C. BACUNGAN, MAECON Director, PPIDO

APPROVED BY:
DR. DENNIS C. DE PAZ University President


SHEET CONTENT:
SECOND FLOOR PLAN

PROJECT ID NO.	SHEET NO.
REV. NO.:	A
DATE SUBMITTED:	4 25

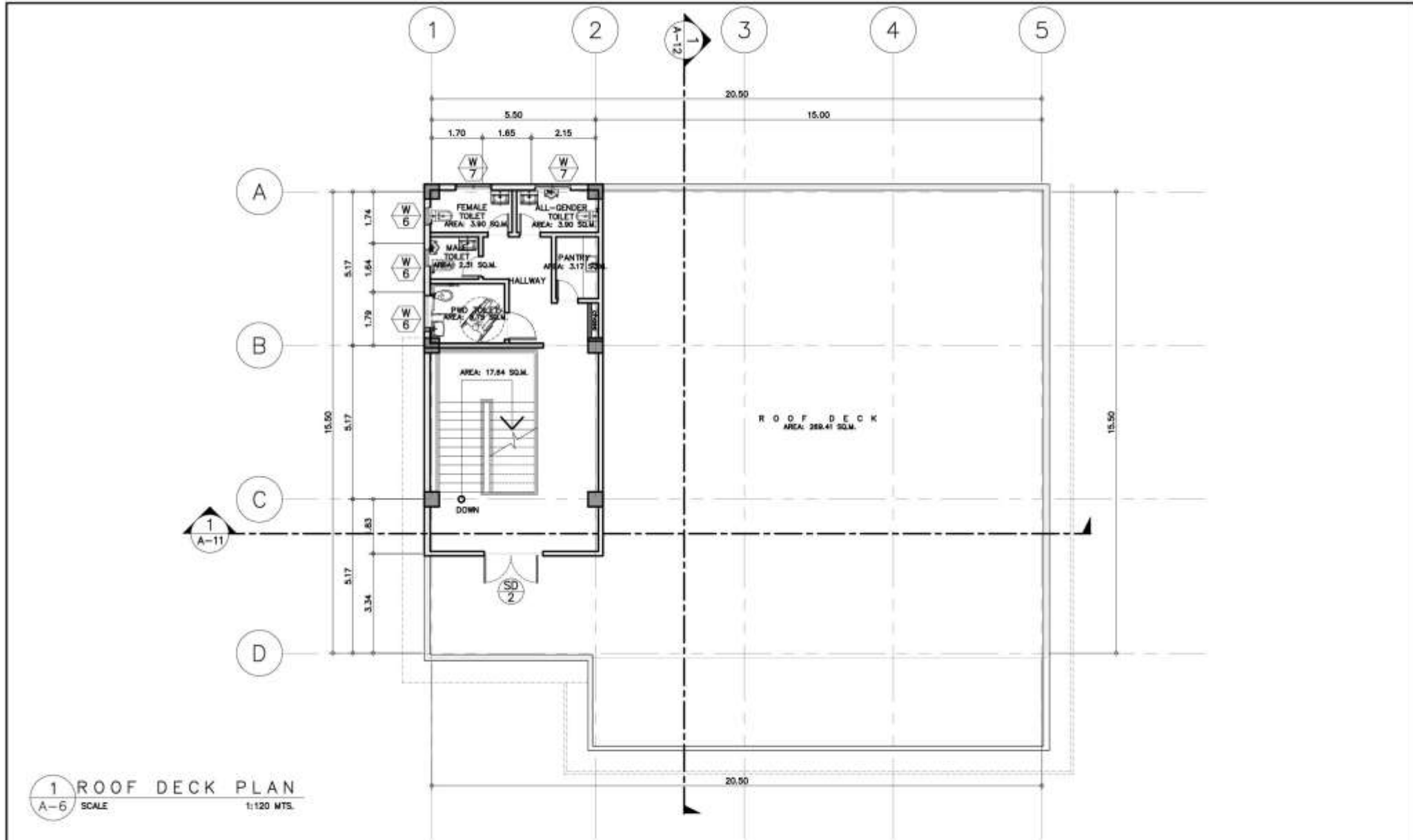
ANNEX “B”




1 THIRD FLOOR PLAN
A-5 SCALE 1:120 MTS.

	PREPARED BY:	ARCHITECT:	R.A. 9296 DRAWINGS AND SPECIFICATION (SEAL, SIGNATURE, STAMP AND SEAL) AS REQUIREMENTS OF SERVICE, ARE THE PROPERTY AND DOCUMENT OF THE ARCHITECT. WHETHER THE OBJECT FOR WHICH THEY ARE MADE IS EXECUTED OR NOT, IT SHALL BE UNLAWFUL FOR ANY PERSON WITHOUT THE WRITTEN CONSENT OF THE ARCHITECT TO DUPLICATE OR MAKE COPIES OF THIS DOCUMENT OF THE WHOLE OR IN PART.	PROJECT TITLE:	RECOMMENDING APPROVAL:	APPROVED BY:	SHEET CONTENT:	PROJECT ID NO.	SHEET NO.
	PPIDO (PHYSICAL PLANNING AND INFRASTRUCTURE DEVELOPMENT OFFICE)	AR. BERNIE G. TUDIG, UAP HEAD, PPIDO		SMART CAMPUS ENHANCEMENT PROGRAM (CONSTRUCTION OF THREE (3) STOREY INNOVATION HUB BUILDING)	PROF. CHRISTOPHER C. BACILINGAN, MAEDON Director, RDC	DR. DENNIS C. DE PAZ University President	THIRD FLOOR PLAN		
	PRC NO. _____ ST. NO. _____ PTR. NO. _____ PL. NO. _____			LOCATION: EVSU-MAIN CAMPUS, TAGLISAN CITY				REV. NO.: _____ DATE SUBMITTED: _____	

ANNEX “B”



1 ROOF DECK PLAN
A-6 SCALE 1:120 MTS.

	PREPARED BY: PPIDO (PHYSICAL PLANNING AND INFRASTRUCTURE DEVELOPMENT OFFICE)	ARCHITECT: AR. BERNE G. TUXO, UAP HEAD, PPIDO	R.A. 2088 DRAWINGS AND SPECIFICATION FULLY SIGNED, STAMPED AND SEALED, AS INSTRUMENTS OF SERVICE, ARE THE PROPERTY AND DOCUMENT OF THE ARCHITECT. WHETHER THE OBJECT FOR WHICH THEY ARE MADE IS EXECUTED OR NOT, IT SHALL BE UNLAWFUL FOR ANY PERSON WITHOUT THE WRITTEN CONSENT OF THE ARCHITECT TO DUPLICATE OR MAKE COPIES OF THIS DOCUMENT OF THE WHOLE OR IN PART.	PROJECT TITLE: SMART CAMPUS ENHANCEMENT PROGRAM (CONSTRUCTION OF THREE (3) STOREY INNOVATION HUB BUILDING)	RECOMMENDING APPROVAL: PROF. CHRISTOPHER C. BACUNGAN, MAECON Director, PPDO	APPROVED BY: DR. DENNIS C. DE PAZ University President	SHEET CONTENT: ROOF DECK PLAN	PROJECT ID NO.	SHEET NO.
	PRC NO. OF. 199 PTR. NO. PL. 199	LOCATION: EYSU-MAIN CAMPUS, TAGBOHAN CITY	REV. NO.: DATE SUBMITTED:	A 6 25					

ANNEX “B”



1 REAR ELEVATION
A-9 SCALE 1:130 MTS.



PREPARED BY:
PPIDO
(PHYSICAL PLANT AND
INFRASTRUCTURE
DEVELOPMENT OFFICE)

ARCHITECT:
AR. BERNIE G. TUDIO, UAP
HEAD, PPID
PRG. NO. 01, PPS
PTR. NO. PL, PSL

P.A. 2006
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PROJECT TITLE:
SMART CAMPUS ENHANCEMENT PROGRAM
(CONSTRUCTION OF THREE (3) STOREY
INNOVATION HUB BUILDING)
LOCATION: EVSU-MAIN CAMPUS, TAGLIBAN CITY

RECOMMENDING APPROVAL:
PROF. CHRISTOPHER C. BACUNGAN, MAECON
Director, PPID

APPROVED BY:
DR. DENNIS C. DE PAZ
University President

SHEET CONTENT:
REAR ELEVATION

PROJECT ID NO.
REV. NO.:
DATE SUBMITTED:

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9 25